Material Composition Specification

SOT-26 Case

Pb (lead)-free plating**

Device average mass . . . . 15.8 mg

Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.54%	0.24	Si	7440-21-3	1.54%	0.243	15,400
bond wire	gold	0.06%	0.01	Au	7440-57-5	0.06%	0.009	570
leadframe	Cu alloy w/ silver plating	40.40%	6.38	Cu	7440-50-8	39.91%	6.305	399,070
				Ag	7440-22-4	0.49%	0.078	4,920
encapsulation*	EMC	53.67%	8.48	silica	7631-86-9	39.71%	6.273	397,050
				epoxy resin	Proprietary	12.49%	1.973	124,870
				Sb_2O_3	1309-64-4	1.08%	0.170	10,760
				TBBA	79-94-7	0.27%	0.043	2,690
				carbon	1333-86-4	0.14%	0.021	1,350
	EMC GREEN	53.67%	8.48	silica	7631-86-9	40.73%	6.435	407,256
				epoxy resin	Proprietary	12.81%	2.024	128,080
				carbon	1333-86-4	0.14%	0.022	1,385
plating**	tin lead process	4.33%	0.68	Sn	7440-31-5	3.40%	0.537	33,980
				Pb	7439-92-1	0.93%	0.148	9,340
	100% tin process	4.33%	0.68	Sn	7440-31-5	4.33%	0.684	43,320

*EMC GREEN molding compound is Halogen-Free.
**Specify Lead-Free when ordering 100% tin (Pb-free) plating.

Disclaimer
The information provided in this Material Composition data sheet is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

Central™
Semiconductor Corp.
www.centralsemi.com

R4 (8-March 2008)